



Material Content Data Sheet



Sales Product Name		SS05N70		Issued		25. September 2017		
MA#		MA001147172						
Package		PG-TO251-3-342		Weight*		317.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.898	0.60	0.60	5968	5968
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		463	
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	copper	7440-50-8	147.096	46.25	46.31	462618	463220
wire	non noble metal	aluminium	7429-90-5	0.546	0.17	0.17	1718	1718
encapsulation	organic material	carbon black	1333-86-4	1.417	0.45		4457	
	plastics	epoxy resin	-	24.802	7.80		78003	
	inorganic material	silicondioxide	60676-86-0	115.507	36.33	44.58	363270	445730
leadfinish	non noble metal	tin	7440-31-5	3.787	1.19	1.19	11910	11910
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4468	4479
solder	noble metal	silver	7440-22-4	0.052	0.02		165	
	non noble metal	tin	7440-31-5	0.042	0.01		132	
	non noble metal	lead	7439-92-1	1.999	0.63	0.66	6287	6584
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60313	60391
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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